



Features

- ◇ The LGE BTA10/BTB10, 10A III & IV quadrants series triacs, which can be operated in III & IV quadrants. As silicon bidirectional device, with NPNPN five-layer structure; singlesided trenching technology, mesa glass passivation process;
- ◇ multi-layer metallized electrode on the back side;
- ◇ High blocking voltage and high temperature stability.

Applications

The LGE BTA10/BTB10 is suitable for inductive load switching operations, also can be used in ON/OFF function applications such as washing machine, induction motor starting circuits, vacuum cleaners, power tools and other motors such as speed control maker; heating regulation, solid state relay; phases control circuit; AC motor speed regulation, and so on.

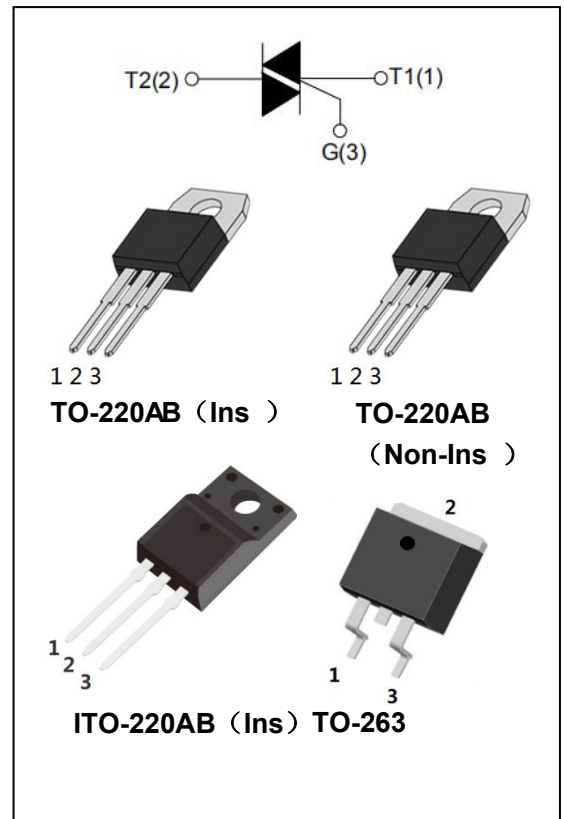
Mechanical Data

- ◇ Moisture Sensitivity: MSL Level 1, per J-STD-020
- ◇ Terminals: Matte Tin Finish.
Solderable per MIL-STD-202 Method 208
- ◇ Case Material: Molded Plastic;
- ◇ Molding compound meet UL Flammability Classification Rating 94V-0
- ◇ Case: JEDEC TO-220AB, ITO-220AB, TO-263

MAXIMUM RATING

Ratings at 25°C ambient temperature unless otherwise specified.

PARAMETER			SYMBOL	VALUE	UNITS
R.M.S. On-State Current	BTA BTB	Tc=80°C Tc=90°C	I _{T(RMS)}	10	A
Non-Repetitive Surge Peak On-State Current (f _{Full Cycle} , T _j initial=25°C)	F=50HZ	T=20ms	I _{TSM}	100	A
	F=60HZ	T=16.7ms		105	
I ² t Value for Fusing	tp=10ms		I ² t	55	A ² s
Critical Rate of Rise of On-State Current I _G =2×I _{GT} , tr≤100ns	F=120HZ	T _j =125°C	di/dt	50	A/μs
Repetitive peak Off-State voltage	T _j =25°C		V _{DRM} /V _{RRM}	600/800	V
Non repetitive surge peak off-state voltage	tp=10ms	T _j =25°C	V _{DSM} /V _{RSM}	V _{DRM} /V _{RRM} +100	V
Peak Gate Current	tp=20μs	T _j =125°C	I _{GM}	4	A
Average Gate Power Dissipation	T _j =125°C		P _{G(AV)}	1	W
Typical Thermal Resistance (Junction to Ambient)	TO-220AB /TO-263		R _{eJA}	50	°C/W
	ITO-220AB			60	
Typical Thermal Resistance (Junction to Case (AC))	TO-220AB (Non-ins)		R _{eJC}	1.6	°C/W
	TO-220AB Ins			2.5	
	ITO-220AB			2.7	
	TO-263			1.7	
Maximum Operating Junction temperature			T _J	-40~+125	°C
Storage temperature range			T _{STG}	-40~+150	°C





ELECTRICAL CHARACTERISTICS(III QUADRANTS)

PARAMETER	TEST CONDITIONS	Symbol	VALUES				Units	
				TW	SW	CW		BW
Gate Trigger Current	VD=12V,RL=100 Ω (I II IIIquadrant)	I _{GT}	MAX	5	10	35	50	mA
Gate Trigger Voltage		V _{GT}	MAX	1.5				V
Gate Non-Trigger Voltage	T _j =125°C (I II IIIquadrant)	V _{GD}	MIN	0.2				V
Holding Current I _T =0.5A		I _H	MAX	10	20	40	60	mA
Latching Current I _G =1.2I _{GT}	I III quadrant	I _L	MAX	20	25	50	70	mA
	II quadrant		MAX	25	35	70	90	
Critical Rate of Rise of Off-State Voltage V _D =2/3V _{DRM} ,T _j =125°C		dv/dt	MIN	200	200	500	1000	V/ μ s
Critical Rate of Rise of Off-State Voltage at Commutation, T _j =125°C		(dv/dt) _c	MIN	5.5	5.5	5.5	10	V/ μ s

ELECTRICAL CHARACTERISTICS(IV QUADRANTS)

PARAMETER	TEST CONDITIONS		SYMBOL	VALUE				UNIT S	
					D	E	F		G
Gate Trigger Current	VD=12V,RL=100 Ω (I II IIIIV quadrant)	I II III	I _{GT}	MAX	5	10	25	50	mA
		IV		MAX	10	25	70	100	
Gate Trigger Voltage		All	V _{GT}	MAX	1.5				V
Gate Non-Trigger Voltage	T _j =125°C (I II IIIquadrant)		V _{GD}	MIN	0.2				V
Holding Current I _T =0.5A			I _H	MAX	10	20	30	60	mA
Latching Current =1.2I _{GT}	I III IVquadrant		I _L	MAX	15	30	40	60	mA
	II quadrant			MAX	20	40	60	90	
Critical Rate of Rise of Off-State Voltage V _D =2/3V _{DRM} ,T _j =125°C			dv/dt	MIN	5	10	200	500	V/ μ s
Critical Rate of Rise of Off-State Voltage at Commutation, T _j =125°C			(dv/dt) _c	MIN	1	2	5.5	10	V/ μ s

STATIC CHARACTERISTICS

PARAMETER	TEST CONDITIONS	SYMBOL		VALUE	UNITS
Peak On-State Voltage	I _{TM} =14A, tp=380 μ s, T _j =25°C	V _{TM}	MAX	1.55	V
Threshold Voltage	T _j =125°C	V _{TO}	MAX	0.85	V
Dynamic Resistance	T _j =125°C	R _d	MAX	40	m Ω
Repetitive Peak Off-Statte Curren V _{DRM} =V _R RM	T _j =25°C	I _{DRM} / I _{RRM}	MAX	5	μ A
	T _j =125°C	I _{DRM} /I _{RRM}	MAX	1	mA



RATING AND CHARACTERISTICS CURVES

FIG.1: Maximum power dissipation versus RMS on-state current

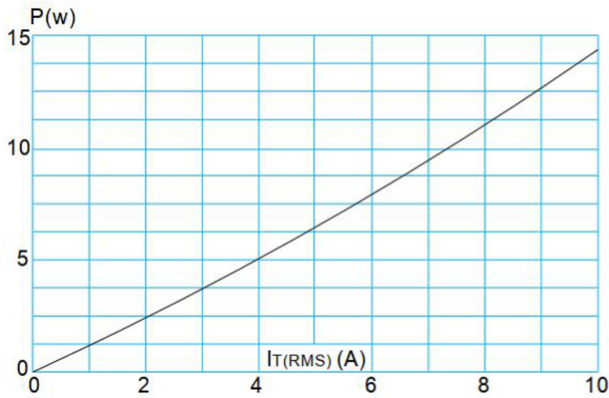


FIG.2: RMS on-state current versus case temperature

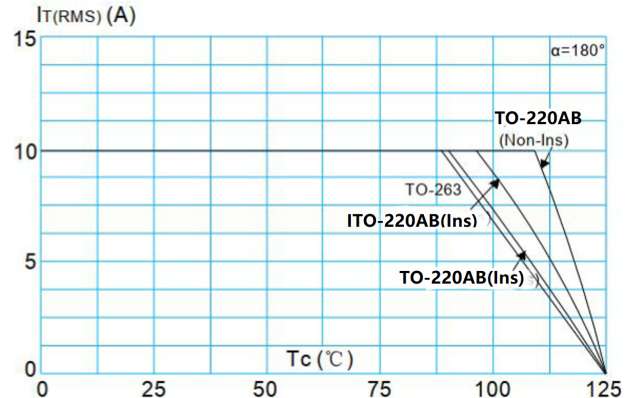


FIG.3: Surge peak on-state current versus number of cycles

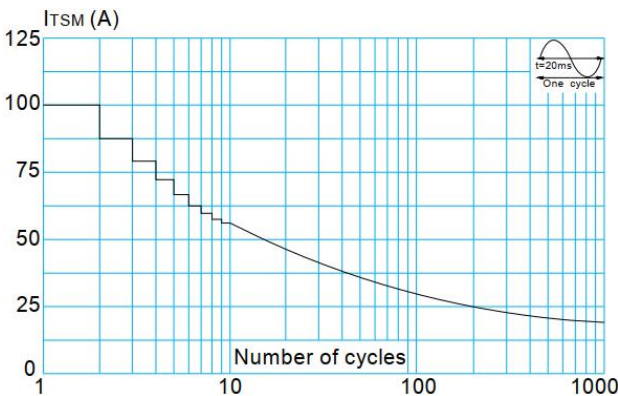


FIG.4: On-state characteristics (maximum values)

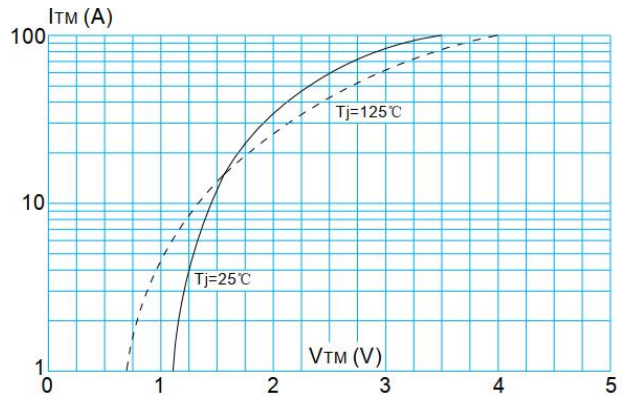


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 20ms$, and corresponding value of I^2t (I - II - III: $dI/dt < 50A/\mu s$; IV: $dI/dt < 10A/\mu s$)

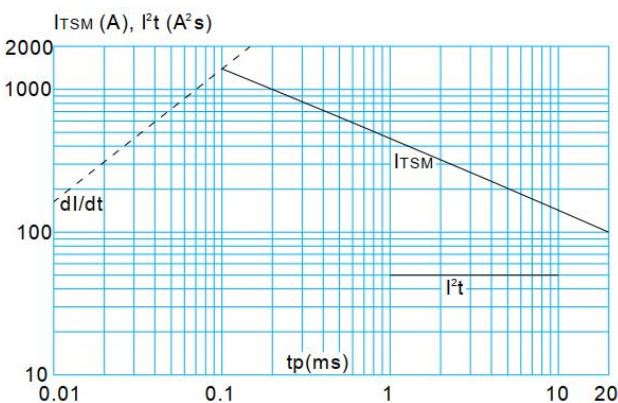
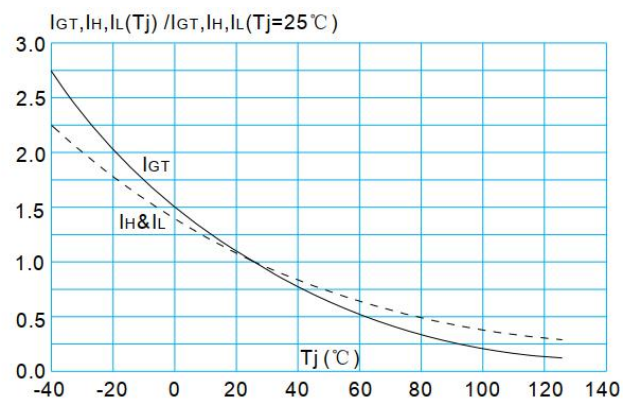


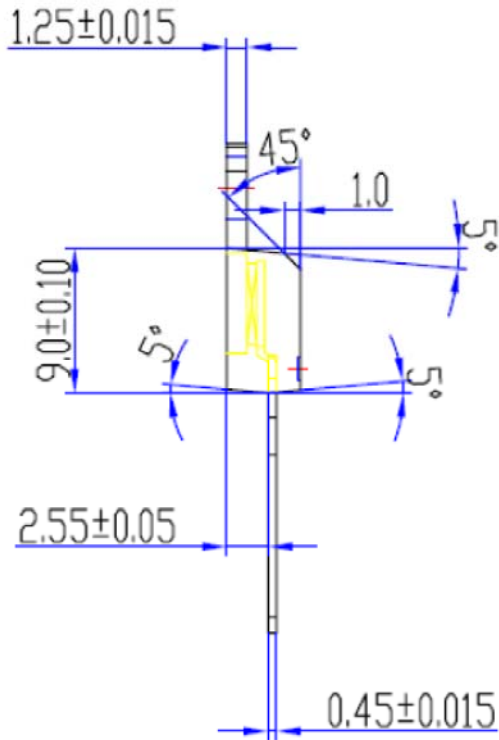
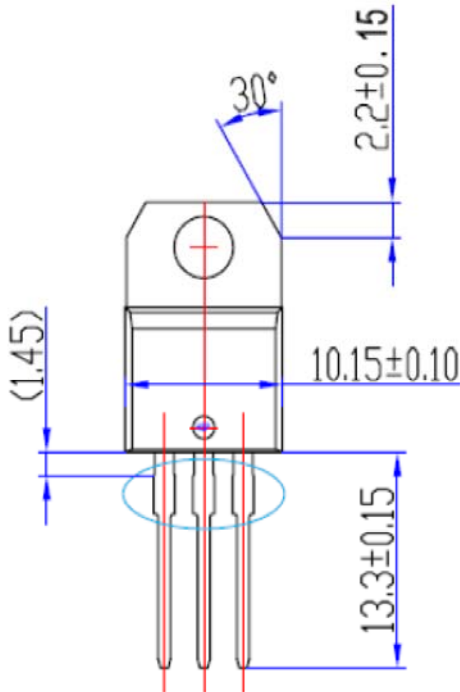
FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature



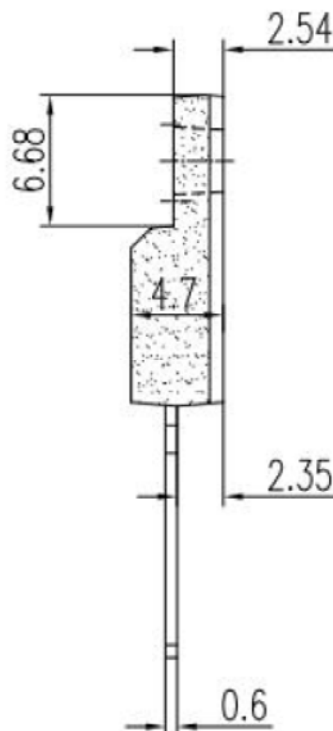
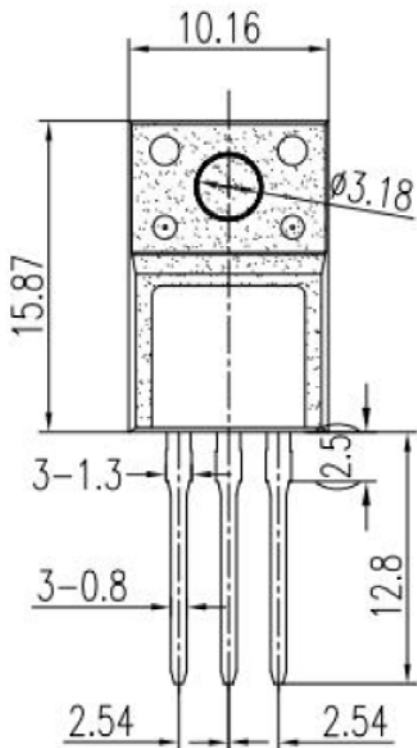


PACKAGE OUTLINE DIMENSIONS

TO-220AB units:mm



ITO-220AB units:mm(±0.10)

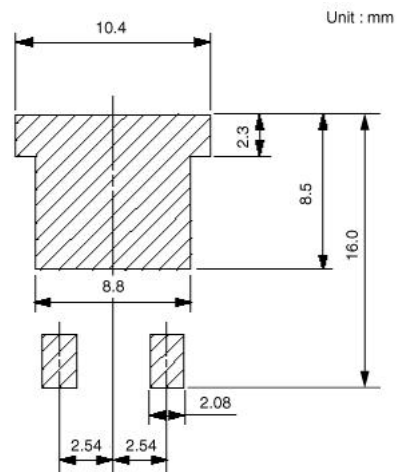
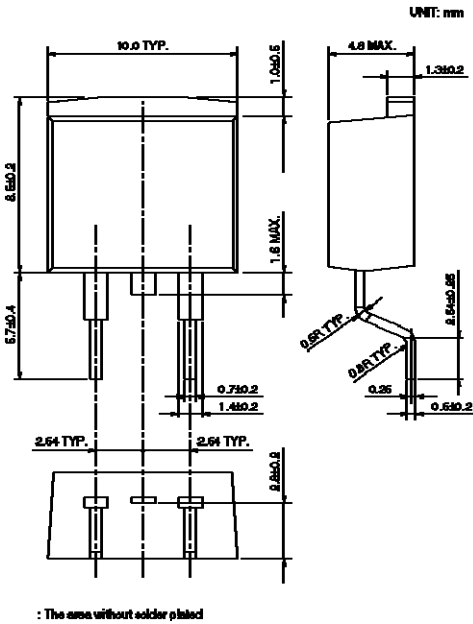




PACKAGE OUTLINE DIMENSIONS

TO-263 units:mm

Suggested Pad Layout



ORDERING INFORMATION

